



SURFACE MOUNT GLASS PASSIVATED RECTIFIER S3AB~ S3MB

Surface Mount Glass Passivated Rectifier

Features

- Glass passivated chip junction
- Built in strain relief
- High current capability
- Low forward voltage drop
- Fast switching speed for high efficiency
- High temperature Soldering guaranteed: 260°C / 10 seconds at terminals
- RoHS and REACH compliance



DO-214AA (SMB)



RoHS
COMPLIANT

Mechanical Data

Case:	JEDEC DO-214AA (SMB), transfer molded plastic
Epoxy:	Meets UL 94V-0 flammability rating
Terminals:	Solder plated, solderable per MIL-STD 750, Method 2026
Polarity:	Cathode indicated by color band
Mounting position:	Any
Weight:	0.003 ounce, 0.093 gram

Maximum Ratings ($T_{Ambient}=25^{\circ}C$ unless noted otherwise)

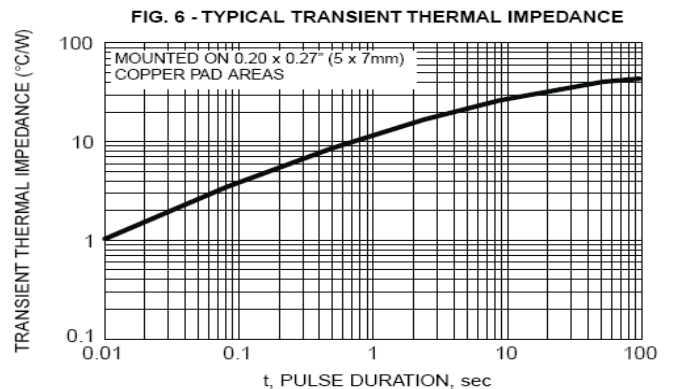
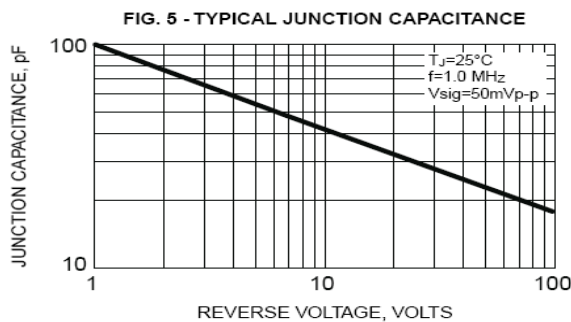
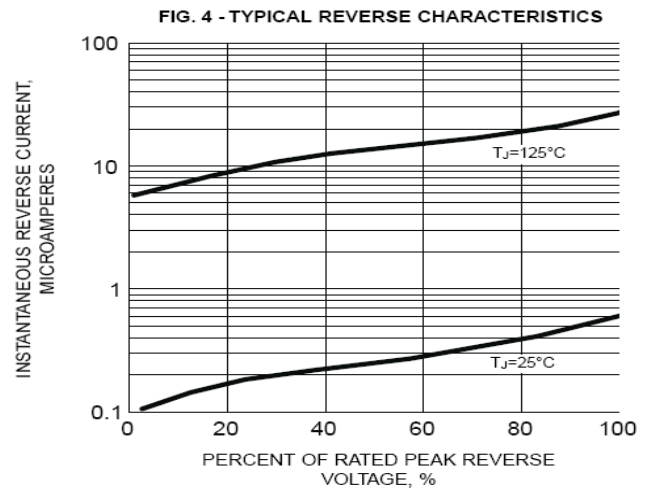
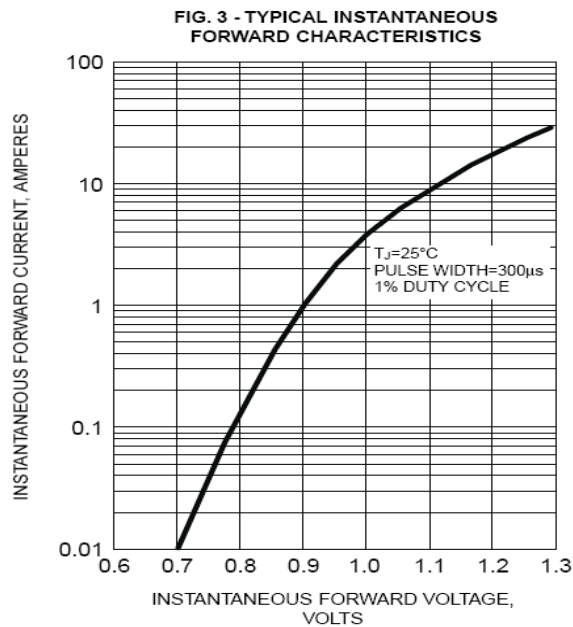
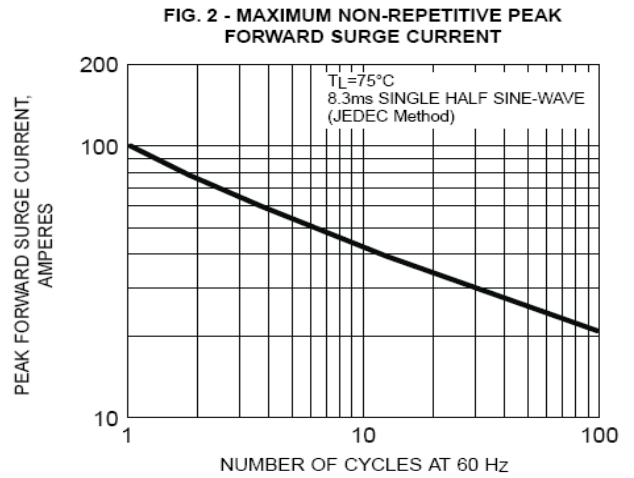
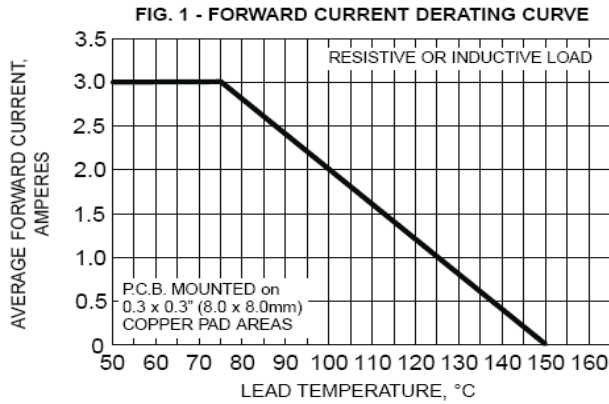
Symbol	Description	S3AB	S3BB	S3DB	S3GB	S3JB	S3KB	S3MB	Unit	Conditions
VRRM	Max Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V	
VRMS	Max RMS Voltage	35	70	140	280	420	560	700	V	
VDC	Max DC Blocking Voltage	50	100	200	400	600	800	1000	V	
I(AV)	Max Average Forward Rectified Current at Ambient Temperature	3.0							A	TL=75°C (note 2)
IFSM	Peak Forward Surge Current	100							A	8.3ms single half sine-wave (JEDEC)
t _{rr}	Maximum Reverse Recovery Time	2.5							µs	IF=0.5A, IR=1.0A, IRR=0.25A
T _J ,T _{STG}	Operating and Storage Temperature Range	-55 to +150							°C	

Electrical Characteristics ($T_{Ambient}=25^{\circ}C$ unless noted otherwise)

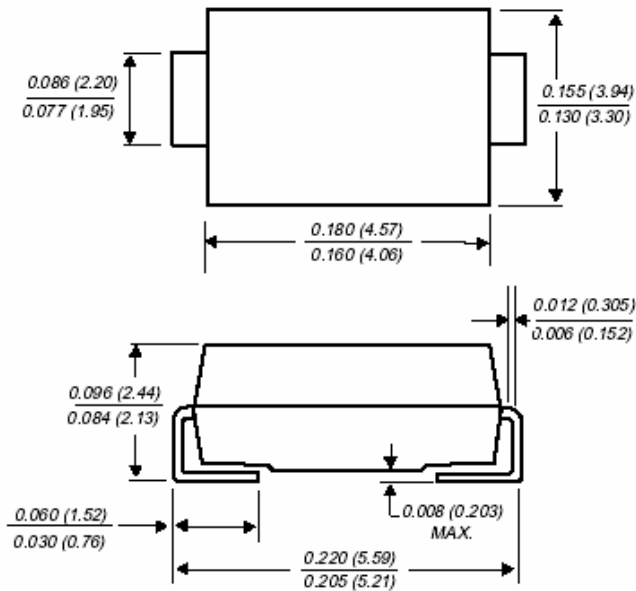
Symbol	Description	S3AB	S3BB	S3DB	S3GB	S3JB	S3KB	S3MB	Unit	Conditions
VF	Max Instantaneous Forward Voltage	1.2							V	IF(AV)= 3.0A
IR	Max DC Reverse Current at Rated DC Blocking Voltage	5.0							µA	TA=25°C
		250								TA=125°C
CJ	Typical Junction Capacitance	60							pF	At 1MHz, reversed voltage of 4V
Rθ-JA	Typical Thermal Resistance	47							°C/W	Note 2
Rθ-JL		13								

Note:

1. Single phase, half wave, 60Hz, resistive or inductive load. Derate current by 20% for capacitive load
2. Thermal Resistance from junction to ambient and from junction to lead mounted on PCB with 0.3" x 0.3" (8.0mm x 8.0mm) copper pad areas.

Typical Characteristics Curves


Dimensions in inch (mm)

*Dimensions in inches and (millimeters)***DO-214AA(SMB)****Contact us:****US HEADQUARTERS****MEI SEMI INC.****2902** Corvin Drive, Santa Clara, CA95051, USA

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